

256K x 8 HIGH-SPEED CMOS STATIC RAM

DECEMBER 2000

FEATURES

- High-speed access times:
 8, 10, 12 and 15 ns
- High-performance, low-power CMOS process
- Multiple center power and ground pins for greater noise immunity
- Easy memory expansion with CE and OE options
- CE power-down
- Low power: 540 mW @ 10 ns 36 mW standby mode
- · TTL compatible inputs and outputs
- Single 3.3V ±10% power supply
- Packages available:
 - 36-pin 400-mil SOJ
 - 44-pin TSOP (Type II)

DESCRIPTION

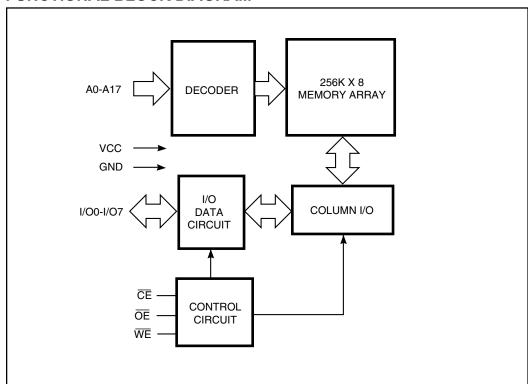
The *ISSI* IS61LV2568 is a very high-speed, low power, 262,144-word by 8-bit CMOS static RAM. The IS61LV2568 is fabricated using *ISSI*'s high-performance CMOS technology. This highly reliable process coupled with innovative circuit design techniques, yields higher performance and low power consumption devices.

When $\overline{\text{CE}}$ is HIGH (deselected), the device assumes a standby mode at which the power dissipation can be reduced down to 36mW (max.) with CMOS input levels.

The IS61LV2568 operates from a single 3.3V power supply and all inputs are TTL-compatible.

The IS61LV2568 is available in 36-pin 400-mil SOJ, and 44-pin TSOP (Type II) packages.

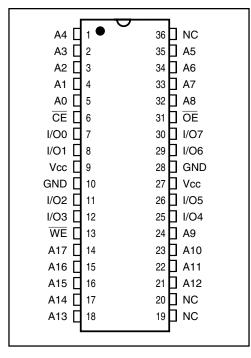
FUNCTIONAL BLOCK DIAGRAM



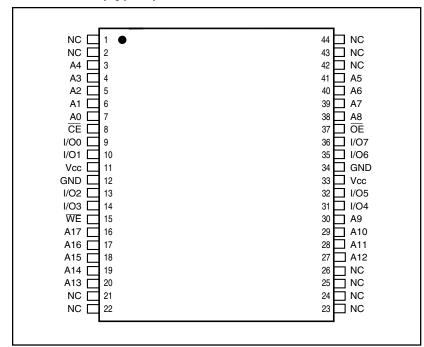
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PIN CONFIGURATION 36-Pin SOJ



44-Pin TSOP (Type II)



PIN DESCRIPTIONS

Address Inputs
Chip Enable Input
Output Enable Input
Write Enable Input
Bidirectional Ports
Power
Ground
No Connection

TRUTH TABLE

Mode	WE	Œ	ŌĒ	I/O Operation	Vcc Current
Not Selected (Power-down)	X	Н	Χ	High-Z	ISB1, ISB2
Output Disable	ed H	L	Н	High-Z	Icc
Read	Н	L	L	D оит	Icc
Write	L	L	Χ	Din	Icc

ABSOLUTE MAXIMUM RATINGS(1)

Symbol	Parameter		Value	Unit
Vcc	Supply voltage with Respect	-0.5 to +4.6	V	
VTERM	Terminal Voltage with Respe	-0.5 to Vcc + 0.5	V	
TBIAS	Temperature Under Bias	Com.	-10 to +85	°C
		Ind.	-45 to +90	
Тѕтс	Storage Temperature		-65 to +150	°C
PD	Power Dissipation		1.0	W

Notes:

 Stress greater than those listed under ABSOLUTE MAXIMUM RATINGS may cause permanent damage to the device. This is a stress rating only and functional operation of the device at these or any other conditions above those indicated in the operational sections of this specification is not implied. Exposure to absolute maximum rating conditions for extended periods may affect reliability.



OPERATING RANGE

Range	Ambient Temperature	V cc
Commercial	0°C to +70°C	3.3V ± 10%
Industrial	–40°C to +85°C	3.3V ± 10%

DC ELECTRICAL CHARACTERISTICS (Over Operating Range)

Symbol	Parameter	Test Conditions		Min.	Max.	Unit
Vон	Output HIGH Voltage	Vcc = Min., Iон = -4.0 mA		2.4	_	V
Vol	Output LOW Voltage	Vcc = Min., IoL = 8.0 mA			0.4	V
VIH	Input HIGH Voltage(1)			2.0	Vcc + 0.3	V
VIL	Input LOW Voltage(1)			-0.3	0.8	V
lu	Input Leakage	GND - Vin - Vcc	Com. Ind.	–1 –5	1 5	μA
lLO	Output Leakage	GND - Vout - Vcc, Outputs Disabled	Com. Ind.	–1 –5	1 5	μA

Note

POWER SUPPLY CHARACTERISTICS⁽¹⁾ (Over Operating Range)

				-8 ns		-10	ns	-12	ns	-15	ns	
Symbol	Parameter	Test Conditions		Min.	Max.	Min.	Max.	Min.	Max.	Min.	Max.	Unit
Icc	Vcc Operating Supply Current	Vcc = Max., \overline{CE} = V _{IL} lout = 0 mA, f = Max.	Com. Ind.	_	150 160	_	125 135	_	110 120	_	90 100	mA
ISB1	TTL Standby Current (TTL Inputs)	Vcc = Max., V _{IN} = V _{IH} or V _{IL} CE • V _{IH} , f = max	Com. Ind.	_	50 60	_	40 50	_	35 45	_	30 40	mA
ISB2	CMOS Standby Current (CMOS Inputs)	Vcc = Max., \overline{CE} - Vcc - 0.2V, Vin > Vcc - 0.2V, or Vin - 0.2V, f = 0	Com. Ind.	_	10 20	_	10 20	_	10 20	_	10 20	mA

Note:

CAPACITANCE(1,2)

Symbol	Parameter	Conditions	Max.	Unit
Cin	Input Capacitance	VIN = 0V	6	pF
Cı/o	Input/Output Capacitance	Vout = 0V	8	pF

Notes

- 1. Tested initially and after any design or process changes that may affect these parameters.
- 2. Test conditions: T_A = 25°C, f = 1 MHz, Vcc = 3.3V.

^{1.} $V_{IL}(min) = -0.3V (DC)$; $V_{IL}(min) = -2.0V (pulse width - 2.0 ns)$. $V_{IH}(max) = V_{CC} + 0.3V (DC)$; $V_{IH}(max) = V_{CC} + 2.0V (pulse width - 2.0 ns)$.

^{1.} At f = fmax, address and data inputs are cycling at the maximum frequency, f = 0 means no input lines change.



READ CYCLE SWITCHING CHARACTERISTICS⁽¹⁾ (Over Operating Range)

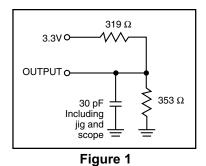
		- 8	ns	-10	ns	-12	ns	-15 n	s	
Symbol	Parameter	Min.	Max	Min.	Max.	Min.	Max.	Min.	Max.	Unit
trc	Read Cycle Time	8	_	10	_	12	_	15	_	ns
t AA	Address Access Time	_	8	_	10	_	12	_	15	ns
tона	Output Hold Time	3	_	3	_	3	_	3	_	ns
tace	CE Access Time	_	8	_	10	_	12	_	15	ns
tDOE	OE Access Time	_	3	_	4	_	5	_	6	ns
tLZOE ⁽²⁾	OE to Low-Z Output	0	_	0	_	0	_	0	_	ns
thzoe(2)	OE to High-Z Output	0	3	0	4	0	5	0	6	ns
tLZCE ⁽²⁾	CE to Low-Z Output	3	_	3	_	3	_	3	_	ns
thzce(2)	CE to High-Z Output	0	3	0	4	0	5	0	6	ns

Notes:

AC TEST CONDITIONS

Parameter	Unit
Input Pulse Level	0V to 3.0V
Input Rise and Fall Times	3 ns
Input and Output Timing and Reference Levels	1.5V
Output Load	See Figures 1 and 2

AC TEST LOADS



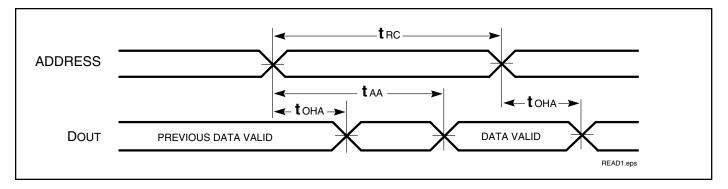
^{1.} Test conditions assume signal transition times of 3 ns or less, timing reference levels of 1.5V, input pulse levels of 0 to 3.0V and output loading specified in Figure 1.

^{2.} Tested with the load in Figure 2. Transition is measured ±200 mV from steady-state voltage. Not 100% tested.

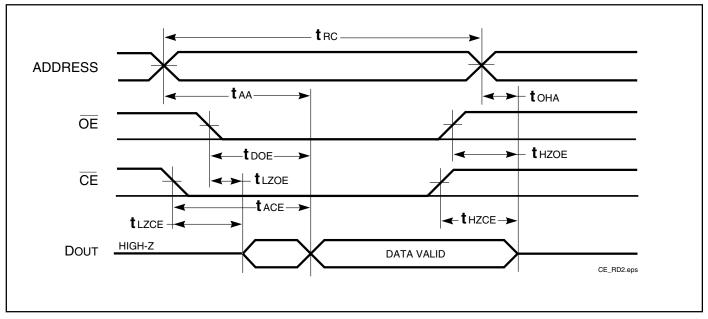


AC WAVEFORMS

READ CYCLE NO. $1^{(1,2)}$ (Address Controlled) ($\overline{CE} = \overline{OE} = V_{IL}$)



READ CYCLE NO. 2^(1,3) ($\overline{\text{CE}}$ and $\overline{\text{OE}}$ Controlled)



- 1. WE is HIGH for a Read Cycle.
- The device is continuously selected. OE, CE = VIL.
 Address is valid prior to or coincident with CE LOW transitions.



WRITE CYCLE SWITCHING CHARACTERISTICS(1,2) (Over Operating Range)

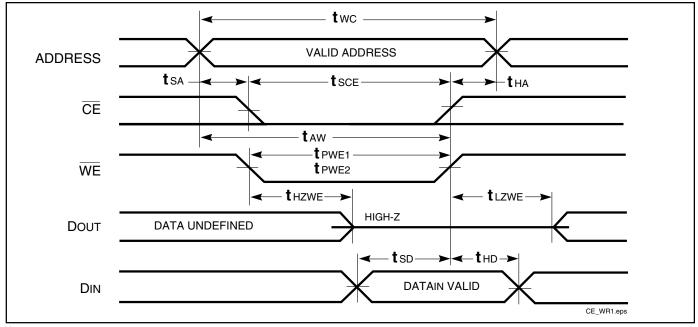
		- 8	ns	-10	ns	-12	ns	-15 n	s	
Symbol	Parameter	Min.	Max	Min.	Max.	Min.	Max.	Min.	Max.	Unit
twc	Write Cycle Time	8	_	10	_	12	_	15	_	ns
tsce	CE to Write End	6.5	_	8	_	9	_	10	_	ns
taw	Address Setup Time to Write End	6.5	_	8	_	9	_	10	_	ns
t HA	Address Hold from Write End	0	_	0	_	0	_	0	_	ns
t sa	Address Setup Time	0	_	0	_	0	_	0	_	ns
tpwe1	WE Pulse Width (OE = HIGH)	5	_	7	_	8	_	10	_	ns
t PWE2	WE Pulse Width (OE = LOW)	6.5	_	8	_	10	_	11	_	ns
tsp	Data Setup to Write End	4	_	5	_	6	_	7	_	ns
t HD	Data Hold from Write End	0	_	0	_	0	_	0	_	ns
thzwe ⁽³⁾	WE LOW to High-Z Output	_	3	_	4	_	5	_	6	ns
tLZWE ⁽³⁾	WE HIGH to Low-Z Output	0		0		0		0	_	ns

Notes:

- 1. Test conditions assume signal transition times of 3 ns or less, timing reference levels of 1.5V, input pulse levels of 0 to 3.0V and output loading specified in Figure 1.
- 2. The internal write time is defined by the overlap of $\overline{\text{CE}}$ LOW and $\overline{\text{WE}}$ LOW. All signals must be in valid states to initiate a Write, but any one can go inactive to terminate the Write. The Data Input Setup and Hold timing are referenced to the rising or falling edge of the signal that terminates the Write.
- 3. Tested with the load in Figure 2. Transition is measured ±500 mV from steady-state voltage. Not 100% tested.

AC WAVEFORMS

WRITE CYCLE NO. $1^{(1,2)}$ (\overline{CE} Controlled, \overline{OE} = HIGH or LOW)



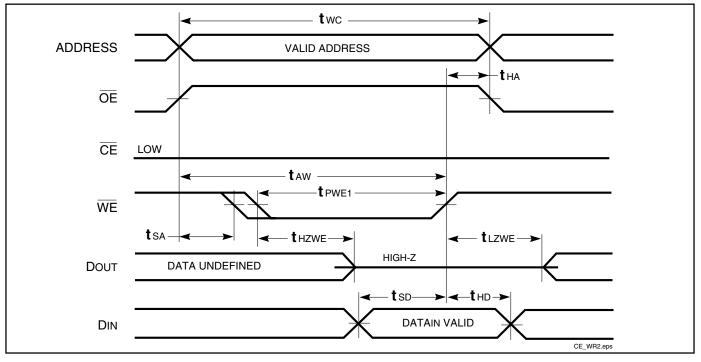
Note:

1. The internal Write time is defined by the overlap of $\overline{\text{CE}}$ = LOW and $\overline{\text{WE}}$ = LOW. All signals must be in valid states to initiate a Write, but any can be deasserted to terminate the Write. The Data Input Setup and Hold timing is referenced to the rising or falling edge of the signal that terminates the Write.



AC WAVEFORMS

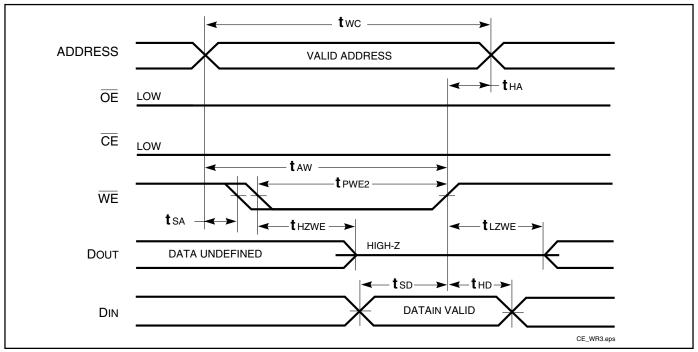
WRITE CYCLE NO. 2⁽¹⁾ (WE Controlled, OE = HIGH during Write Cycle)



Note:

1. The internal Write time is defined by the overlap of $\overline{\text{CE}}$ = LOW and $\overline{\text{WE}}$ = LOW. All signals must be in valid states to initiate a Write, but any can be deasserted to terminate the Write. The Data Input Setup and Hold timing is referenced to the rising or falling edge of the signal that terminates the Write.

WRITE CYCLE NO. 3 (WE Controlled: OE is LOW During Write Cycle)



Note

1. The internal Write time is defined by the overlap of $\overline{\text{CE}}$ = LOW and $\overline{\text{WE}}$ = LOW. All signals must be in valid states to initiate a Write, but any can be deasserted to terminate the Write. The Data Input Setup and Hold timing is referenced to the rising or falling edge of the signal that terminates the Write.



ORDERING INFORMATION

Commercial Range: 0°C to +70°C

Speed (ns)	Order Part No.	Package
8	IS61LV2568-8K IS61LV2568-8T	400-mil Plastic SOJ TSOP (Type II)
10	IS61LV2568-10K IS61LV2568-10T	400-mil Plastic SOJ TSOP (Type II)
12	IS61LV2568-12K IS61LV2568-12T	400-mil Plastic SOJ TSOP (Type II)
15	IS61LV2568-15K IS61LV2568-15T	400-mil Plastic SOJ TSOP (Type II)

ORDERING INFORMATION

Industrial Range: -40°C to +85°C

Speed (ns)	Order Part No.	Package
8	IS61LV2568-8KI IS61LV2568-8TI	400-mil Plastic SOJ TSOP (Type II)
10	IS61LV2568-10KI IS61LV2568-10TI	400-mil Plastic SOJ TSOP (Type II)
12	IS61LV2568-12KI IS61LV2568-12TI	400-mil Plastic SOJ TSOP (Type II)
15	IS61LV2568-15KI IS61LV2568-15TI	400-mil Plastic SOJ TSOP (Type II)



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